

## P-Channel Enhancement Mode Field Effect Transistor

### Product Summary

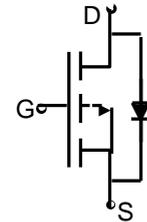
- $V_{DS}$  -60 V
- $I_D$  -0.17 A
- $R_{DS(ON)}$ ( at  $V_{GS}=-10V$ ) <8 ohm
- $R_{DS(ON)}$ ( at  $V_{GS}=-4.5V$ ) <10 ohm

### General Description

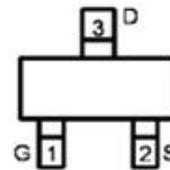
- Trench Power LV MOSFET technology
- Low  $R_{DS(ON)}$
- Low Gate Charge

### Applications

- Video monitor
- Power management



Schematic diagram



Marking and pin Assignment



SOT23 top view

### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	$V_{DS}$	-60	V
Gate-source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$T_A=25^\circ\text{C}$ @ Steady State	-0.17	A
	$T_A=70^\circ\text{C}$ @ Steady State	-0.14	
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	-0.68	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	$P_D$	225	mW
Thermal Resistance Junction-to-Ambient <sup>B</sup>	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BSS84	F2		3000	30000	120000	7" reel

**■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250μA	-60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V, T <sub>C</sub> =25°C			-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.9	-1.4	-2.0	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> =-0.15A			8	Ω
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-0.15A			10	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-0.17A, V <sub>GS</sub> =0V			-1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				-0.17	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, f=1MHZ		30		pF
Output Capacitance	C <sub>oss</sub>			10		
Reverse Transfer Capacitance	C <sub>rss</sub>			5		
<b>Switching Parameters</b>						
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =-4.5V, V <sub>DD</sub> =-30V, I <sub>D</sub> =-0.15A, R <sub>GEN</sub> =2.5Ω		2.5		ns
Turn-on Rise Time	t <sub>r</sub>			1		
Turn-off Delay Time	t <sub>D(off)</sub>			16		
Turn-off Fall Time	t <sub>f</sub>			8		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

■ Typical Performance Characteristics

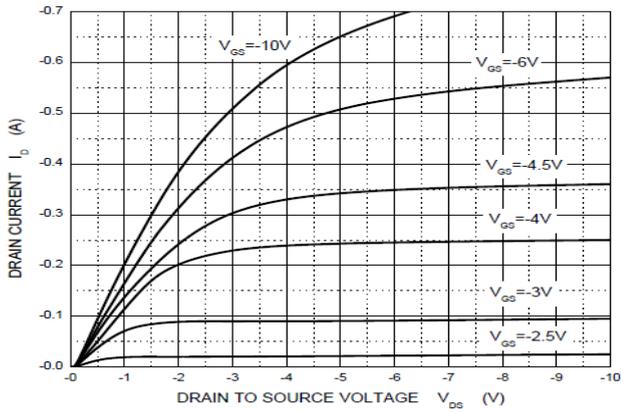


Figure1. Output Characteristics

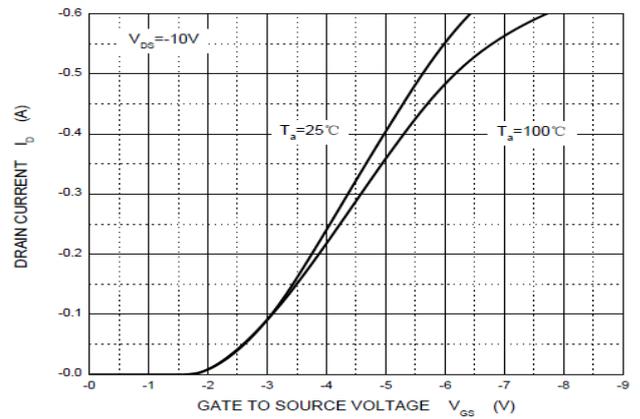


Figure2. Transfer Characteristics

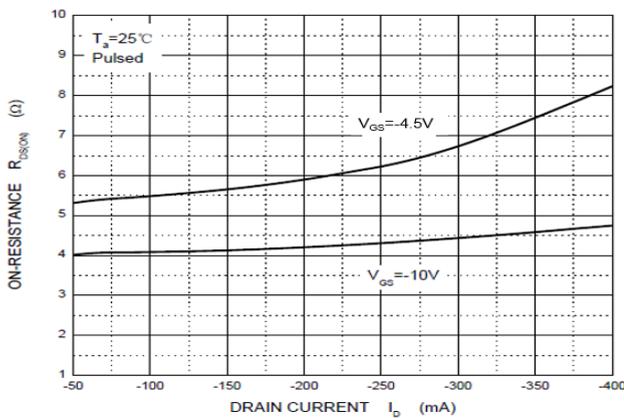


Figure3. Drain-Source on Resistance

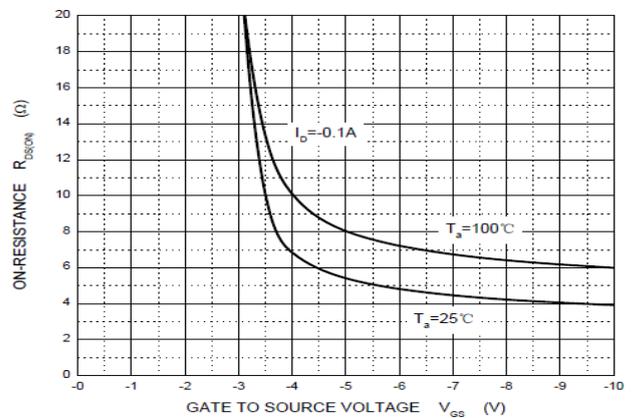


Figure4. Drain-Source on Resistance

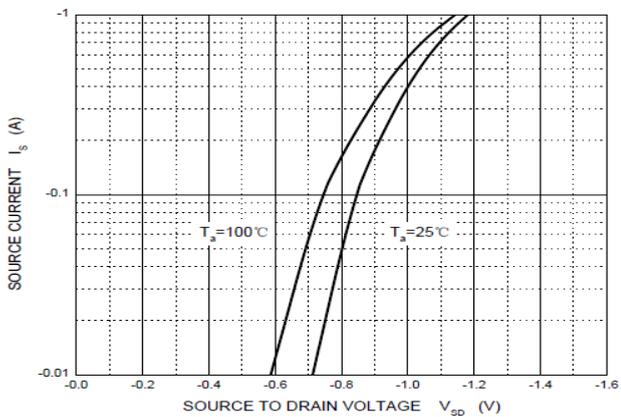


Figure5. Diode Forward Voltage vs. current

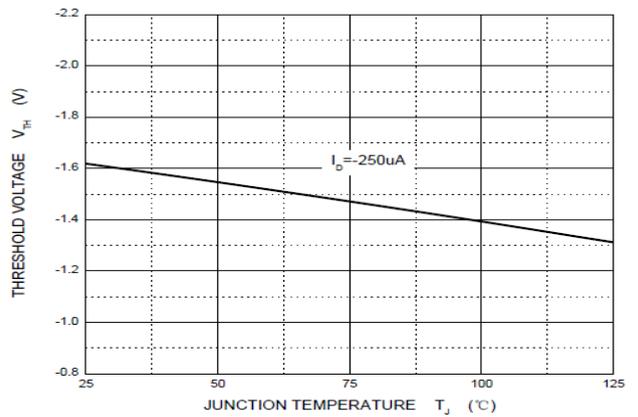
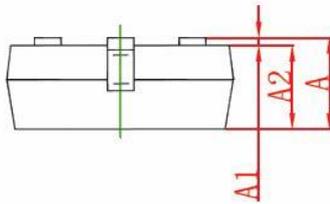
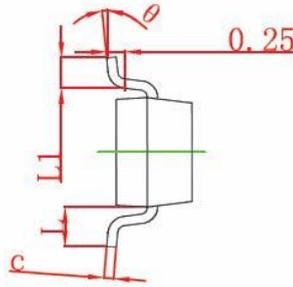
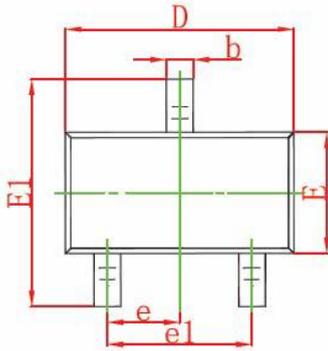
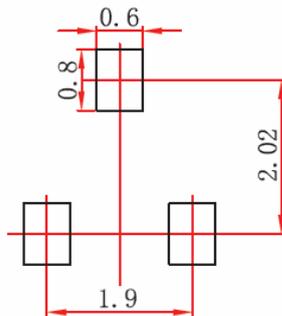


Figure6. Gate Threshold vs. Junction Temperature

**■ SOT-23 Package information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
$\theta$	0°	8°	0°	8°

**■ SOT-23 Suggested Pad Layout**

**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

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